

# OL-NX3P1108UK

wafer level chip-size package; 4 bumps; 0.96 x 0.96 x 0.55 mm (Backside coating included)

10 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	X (other)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	2-7-2012

Table 1. Package summary

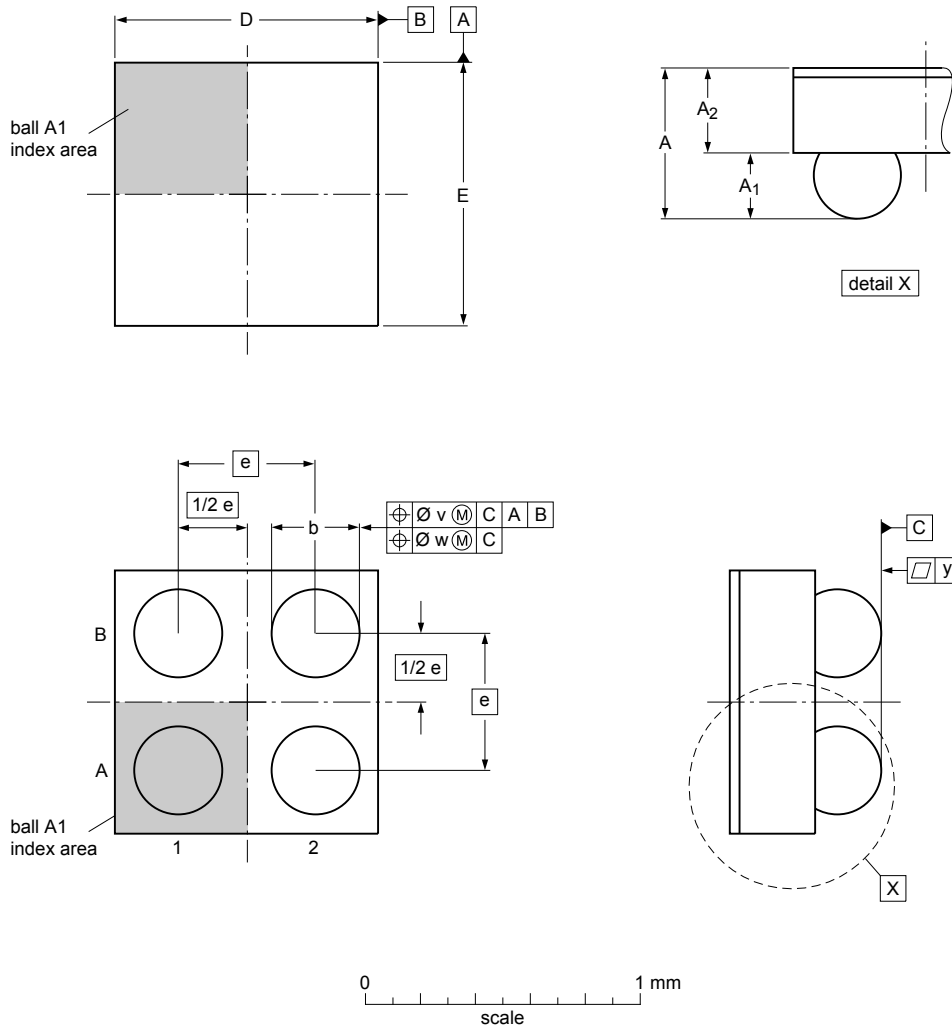
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.94	-	0.96	0.98	mm
E	package width	0.94	-	0.96	0.98	mm
A	seated height	0.51	-	0.55	0.59	mm
A <sub>2</sub>	package height	0.285	-	0.31	0.335	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	4	-	



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## 2. Package outline

WLCSP4: wafer level chip-size package; 4 bumps; 0.96 x 0.96 x 0.55 mm (Backside coating included) NX3P1107/NX3P1108



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	v	w	y
max	0.59	0.27	0.335	0.35	0.98	0.98				
mm nom	0.55	0.24	0.310	0.32	0.96	0.96	0.5	0.02	0.015	0.03
min	0.51	0.21	0.285	0.29	0.94	0.94				

wlcs4\_nx3p1107-8\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
NX3P1107/NX3P1108					-12-06-22- 12-07-02

Fig. 1. Package outline WLCSP (OL-NX3P1108UK)

wafer level chip-size package; 4 bumps; 0.96 x  
0.96 x 0.55 mm (Backside coating included)

### 3. Legal information

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